

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application. The following listing provides the amended claims with deleted material crossed out and new material underlined to show the changes made.

**Listing of Claims:**

1. (Amended) An integrated circuit ("IC") layout comprising:

a first set of vias that have a diamond shape, wherein each via in the first set of vias traverses at least two layers of the IC layout and has a contact on each of the layers, wherein each contact is in the shape of a diamond; and

a first set of interconnect lines, wherein each interconnect line in the first set has an end that has a shape of a partial polygon and that terminates on at least one diamond-shaped contact, wherein the polygon has more than four sides ~~and a second set of vias that have a rectangular shape.~~

2. (Amended) The layout of claim 1 further comprising a second set of vias wherein ~~each a first~~ via in the ~~second~~first set of vias traverses two layers of the IC layout and ~~the first via has a contact on each of the layers, wherein each~~ has at least one contact ~~is in the shape of a rectangular diamond.~~

3. (Amended) The IC layout of claim 2 further comprising a second set of interconnect lines, wherein each interconnect line in the second set has an end that has a shape of a partial polygon and that terminates on at least one rectangular-shaped contact, wherein the polygon has more than four sides ~~wherein a second via in the second set traverses two layers of~~

~~the IC layout and the second via has a contact on each of the layers, wherein each contact of the second via is in the shape of a rectangle.~~

4. (Original) An integrated-circuit ("IC") layout comprising:  
a first set of vias, wherein each via in the first set traverses at least two layers and has one contact on each of the layers, wherein one of the contacts is in the shape of a rectangle and one of the contacts is in the shape of a diamond;  
a first set of interconnect lines terminating on at least a plurality of the first set of vias, wherein the interconnect lines in the first set of interconnect lines have ends that terminate on said contacts, wherein a plurality of the interconnect lines ends are in the shape of a half polygon, wherein the polygon has more than four sides.

5. (Original) The IC layout of claim 4, wherein the rectangle is a square.

6. (Original) The IC layout of claim 4, wherein the rectangle has a different length and width.

7. (Original) The IC layout of claim 4, wherein the diamond has four equal sides.

8. (Original) The IC layout of claim 4, wherein the diamond has two pairs of sides, wherein the length of one pair of sides is different than the length of the other pair of sides.

9. (Original) An integrated circuit ("IC") layout comprising a first set of vias, wherein each via in the first set traverses at least two layers and has one contact on each of the layers, wherein one of the contacts is in the shape of a quadrilateral polygon and one of the contacts is in the shape of a non-quadrilateral polygon.

10. (Original) The IC layout of claim 4, wherein the interconnect line ends are in the shape of a half-octagon.

11. (Original) The IC layout of claim 4, wherein the interconnect line ends are in the shape of a half-hexagon.

12. (Original) The IC layout of claim 4, wherein the interconnect lines with half polygonal ends terminate on the diamond shaped contacts.